SOLDER PASTE SC 126

Type ISO 1.2.2.C

The solder paste SOLDER CHEMISTRY SC 126 is a high tech product especially suitable for all SMT applications. Not only many years of experience in the SMT field, but also the careful and strict consideration of DIN-, SC-, IPC-, and MIL- standards were part of a complete development for the future.
SC 126 is a homogeneous mixture of solder powder, in all required alloys and grain sizes, and an organic flux based on synthetic rosin, corresponding to class RE L1 according to J-STD-005 or RMA-qualification.
Besides an excellent slump resistance, no solder balling, a long stencil and tack life and high temperature stability, this paste has following advantages:

SC 126 a paste with few solid substances, resulting in 4.6% of residue
SC 126 residues corresponding to the ISO 1.2.2.C and RE L0 qualification
SC 126 contains corrosion inhibitors
SC 126 an outstanding quality of prints - for hours
SC 126 excellent even for fine pitch applications
SC 126 works even on slightly corroded areas

PHYSICAL PROPERTIES:
Preferred alloys of solder powder: 62Sn/36Pb/2Ag and 63Sn/37Pb

Grain size definition:

SC 126	DIN 32 513	Diameter	Mesh size
Fine (F)	class 3	20-45 µm	325-500
Superfine (SF)	class 4	15-30 µm	400-700

VISCOSITY (Pa.s) +/-10% measured with Brookfield RVT-DV-II viscometer at 90% metal content

Grain size	Viscosity
Fine (F)	650-800

S.I.R. AND ELECTROMIGRATION comparable to DIN 32513

Day measured	4th	$\underline{21^{st}}$
	$1.2 \cdot 10^{12}$	$8.8 \cdot 10^{11}$

Qualification

SC 126 is an RMA paste, which fulfils the demands of MIL-QQ-S571e. The corrosion-, solderballing-, wetting- and slump tests have been passed. Laboratory tests certify non-corrosive residues, according to RE L0, which can be left on the board. The modified rosin composition guarantees no tar residues in the reflow oven.

Storage

Unopened at room temperature (20℃/68℉): 6 months
Open or on the printer squeegee, the maximal processing time, of course, depends on the environmental influences on the paste.

Application information

After using the paste close the container tightly.
Do not mix used and fresh paste, only to freshen up paste and only at work in progress.
Do not mix pastes of different kind.
Recommended squeegee speed: 15-100 mm/s.
For stencil printing, paste with 90% metal content is recommended.
Note: the printer is always faster than the fastest assembler in the production line.
The printer squeegee must be set to ensure that the paste performs a rolling action in front of the squeegee and does not slide!
The stencil can be washed with an alcohol mixture (We recommend the SC Stencil Cleaner). The alcohol must not contaminate fresh paste.
The paste is suitable for all common reflow systems.

Solder Chemistry order example

Paste	Grain size	Alloy	Flux content	Jar capacity
SC 126	F	62/36/2Ag	10%	500 g
SC 126	F	63/37	10%	500 g

Order example after DIN:

Solder paste (SC...) L-Sn62Pb2Ag / F-SW26 / 90-3 500 g (packing)

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